OIP ETSMC-03-337
DEC 1 0 2003

December 1, 2003

To: Commissioner for Patents

P.O.Box 1450

Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572

28 Davis Avenue

Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/655,689 09/05/03

Yian-Liang Kuo et al.

AN SBGA DESIGN FOR LOW-K INTEGRATED

CIRCUITS (IC)

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation In An Application.

The following Patents and/or Publications are submitted to comply with the duty of disclosure under CFR 1.97-1.99 and 37 CFR 1.56. Copies of each document is included herewith.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on December (), 2003.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

12/8/03

TSMC-03-337

- U.S. Patent 5,977,633 to Suzuki et al., "Semiconductor Device with Metal Base Substrate Having Hollows," describes a semiconductor device with metal base substrate having hollows.
- U.S. Patent 5,223,741 to Bechtel et al., "Package for an Integrated Circuit," describes a package for an integrated circuit structure.
- U.S. Patent 5,585,671 to Nagesh et al., "Reliable Low Thermal Resistance Package for High Power Flip Clip IC's," describes a low thermal resistance package for high power flip chip IC's.
- U.S. Patent 6,462,410 to Novotny et al., "Integrated Circuit Component Temperature Gradient Reducer," describes an integrated circuit component temperature gradient reducer.
- U.S. Patent 4,748,495 to Kucharek, "High Density Multi-Chip Interconnection and Cooling Package," describes a high density mulitchip interconnection and cooling package.

Sincerely,

Stephen B. Ackerman,

Reg. No. 37761

1 AUTO-1	1 Ph 2 70-1449					TSMC-03-337 10/655, 689				
_ ^	RMATION			HOITATIC	Apparent V.	1	1.	<u> </u>		
1 0 2003			CATION		rung on a lang kno et al					
1.3 1.5	(Use several :	3N00(3 N6	C0333JY)	LI C' DATE	NT DOCUMENTS		·	<u>.</u>		
EXAMINER MIAL	DOCUMENT HUMBER DATE		l DATE	U. S'. PATENT DOCUMENTS			CLASS SUBCLASS MUND DATE			
	0000-211				<u></u>			* APPROPULT		
	5977	633	11/2/99	Suzuk	i et al.	257	738	5/29	198	
	5223	741	6/29/93	Bech	rel et al.	257	678	9/11	18-9	
	5585	671	12/17/90	Nages	het d.	257	697	10/7	19	
	6462	410	10/8/02		3	257	707	8/17	1/0	
	4748	495	5/3/18	Kucha	rek	357	82	8/8	1/8	
			TE TE							
<u></u>										
	 - -	111.						·	•	
		+++							· · · · <u>-</u> .	
			J	FORFIGNERA	TENT DOOLULEN	To				
	DOCUMENT NUMBER				TENT DOCUMENTS	cuss	subclass	Translat	ilon	
		T	wie -				3000033	YES	W	
		 			·					
				~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~	····	•				
						·				
,			·							
	·	4	<del></del>	OTHER DOC	UMENTS (Induano	Author, Title, D	ale, Pertinent	Pagas, Elc.	.,	
			,			<del></del>	<del></del>	<del></del>	•	
			<del></del>		·	·	P		<del></del>	
	}	<del></del>								
<del></del>					DATE CONMIDERED				·.	
EXAMPLER					1					